

DERWENT-ACC-NO: 1998-548542

DERWENT-WEEK: 199847

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TITLE: Ball grid array type semiconductor integrated circuit device with heat spreader - has hook structure formed on heat sink, to hook and connect sealing resin of package with heat sink

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PRIORITY-DATA: 1997JP-0040205 (February 25, 1997)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP <u>10242355</u> A	September 11, 1998	N/A	006	H01L 023/40

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP 10242355A	N/A	1997JP-0040205	February 25, 1997

INT-CL (IPC): H01L023/12, H01L023/28, H01L023/40

ABSTRACTED-PUB-NO: JP 10242355A

BASIC-ABSTRACT:

The device (3) has a heat sink (1) provided on the rear surface of the package along the principal plane. A hook- structure (1A) formed on the heat sink, hooks and connects the sealing resin (2) of the package with the heat sink.

ADVANTAGE - Increases contact area of heat sink and sealing resin and thereby offers effective heat dissipation. Reduces peeling off and crack generation of sealing resin boundary surface due to thermal expansion.

CHOSEN-DRAWING: Dwg.1/6

TITLE-TERMS: BALL GRID ARRAY TYPE SEMICONDUCTOR INTEGRATE CIRCUIT
DEVICE HEAT

SPREAD HOOK STRUCTURE FORMING HEAT SINK HOOK CONNECT SEAL RESIN
PACKAGE HEAT SINK

DERWENT-CLASS: U11

EPI-CODES: U11-D01A1; U11-D01A3; U11-D02B2; U11-E02A1;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N1998-427770